

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5521068

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHAN LAM CHA	04/30/2019
WEI HAN KOO	04/30/2019
THORSTEN MEYER	04/30/2019
KLAUS SCHIESS	05/02/2019
GUAN CHOON MATTHEW NELSON TEE	05/02/2019
RECEIVING PARTY DATA	
Name:	INFINEON TECHNOLOGIES AUSTRIA AG
Street Address:	SIEMENSSTRASSE 2
City:	VILLACH
State/Country:	AUSTRIA
Postal Code:	9500
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16397219
CORRESPONDENCE DATA	
Fax Number:	(919)948-3357
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	919-948-3390
Email:	official@mbhiplaw.com
Correspondent Name:	MURPHY, BILAK & HOMILLER/INFINEON TECHNO
Address Line 1:	1255 CRESCENT GREEN
Address Line 2:	SUITE 200
Address Line 4:	CARY, NORTH CAROLINA 27518
ATTORNEY DOCKET NUMBER:	1012-2381 / 2019P50177 US
NAME OF SUBMITTER:	JAMES MICHAEL O'NEILL
SIGNATURE:	/James M. O'Neill, Reg. #69,924/
DATE SIGNED:	05/14/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 8

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**DECLARATION AND ASSIGNMENT
FOR PATENT AND DESIGN APPLICATIONS**

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

Semiconductor Device with Bond Pad Extensions Formed on Molded Appendage

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following:

United States Application Number or PCT International Appln. No. 16/397,219

filed on Apr 29, 2019.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

WHEREAS, the undersigned has invented certain at least one claim in the application identified.

WHEREAS, Infineon Technologies Austria AG

of Siemensstrasse 2 Villach, Austria 9500

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

☒ in any foreign countries.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these considerations does (do) sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions of all of the above for the full term or terms for which the same may be granted.

The undersigned agrees to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof or any other proceedings before the United States Patent and Trademark Office and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agrees to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned hereby authorizes and requests the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has the full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grants the Assignee's legal representatives the power to insert, before or after this document has been executed by the undersigned, any information to identify the instant patent application which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office.

The undersigned hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

The undersigned hereby acknowledges that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Chan Lam Cha

Inventor Signature

Wei Han Koo

Inventor Signature

Thorsten Meyer

Inventor Signature

Klaus Schiess

Inventor Signature

Guan Choon Matthew Nelson Tee

Inventor Signature _____

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Full Name of Inventor:

Chan Lam Cha

Date

Inventor Signature

Full Name of Inventor:

Wei Han Koo

Date

Inventor Signature

Full Name of Inventor:

Thorsten Meyer

Date

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Full Name of Inventor:

Klaus Schiess

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Full Name of Inventor:

Guan Choon Matthew Nelson Tee

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Date

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Full Name of Inventor:

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